

SCOPE OF CLAIMED INVENTION:

- 5u(694)
1. A semiconductor device characterized in comprising:
    - a first semiconductor chip mounted on a substrate;
    - a second semiconductor chip mounted on the first semiconductor chip, the second semiconductor chip being larger than the first semiconductor chip;
    - a base member that is disposed between the second semiconductor chip and the substrate; and
    - a connection member disposed below the substrate,
 wherein the second semiconductor chip is supported by the base member.
  
  2. A semiconductor device characterized in comprising:
    - a first semiconductor chip mounted on a substrate;
    - a second semiconductor chip mounted on the first semiconductor chip, the second semiconductor chip being larger than the first semiconductor chip;
    - a filler layer that is provided between the second semiconductor chip and the substrate; and
    - a connection member disposed below the substrate,
 wherein the second semiconductor chip is supported by the filler layer.
  
  3. A method for manufacturing a semiconductor device, the method characterized in comprising the steps of:
    - mounting a first semiconductor chip on a substrate;
    - mounting a base member outside the first semiconductor chip on the substrate; and
    - mounting a second semiconductor chip that is larger than the first semiconductor chip on the first semiconductor chip, in a manner that the second semiconductor chip is supported by the base member.

4. A method for manufacturing a semiconductor device, the method characterized in comprising the steps of:

- mounting a first semiconductor chip on a substrate,
- mounting a second semiconductor chip that is larger than the first semiconductor chip on the first semiconductor chip; and
- providing a filler layer in a manner to support the second semiconductor chip.

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cont.

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